

## Automotive power Schottky rectifier

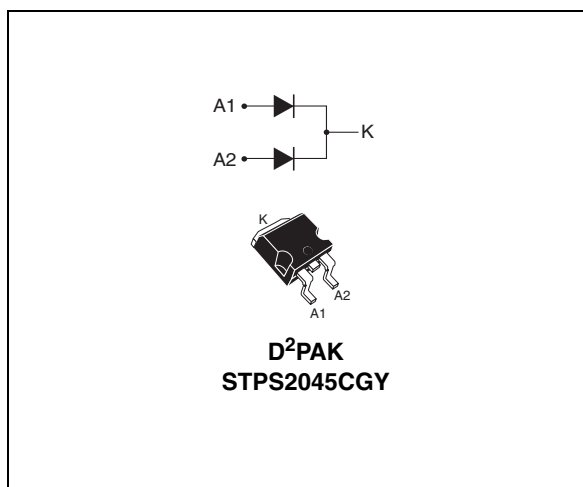
### Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Avalanche rated
- AEC-Q101 qualified

### Description

Dual center tap Schottky rectifier suited for high frequency DC to DC converters.

Packaged in D<sup>2</sup>PAK, this device is especially intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



**Table 1. Device summary**

$I_{F(AV)}$	2 x 10 A
$V_{RRM}$	45 V
$T_{j(max)}$	175 °C
$V_{F(typ)}$	0.57 V

# 1 Characteristics

**Table 2. Absolute ratings (limiting values, per diode)**

Symbol	Parameter			Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage			45	V
I <sub>F(RMS)</sub>	Forward rms current			30	A
I <sub>F(AV)</sub>	Average forward current δ = 0.5	T <sub>c</sub> = 155 °C	Per diode	10	A
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal		180	A
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 1 μs, T <sub>j</sub> = 25 °C		4000	W
T <sub>stg</sub>	Storage temperature range			-65 to +175	°C
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>			-40 to +175	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/μs

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistances parameters**

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	2.2	$^{\circ}\text{C/W}$
		Total	1.3	
$R_{th(c)}$	Coupling		0.3	$^{\circ}\text{C/W}$

When the diodes 1 and 2 are used simultaneously :

$$T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{th(j-c)}(\text{per diode}) + P(\text{diode } 2) \times R_{th(c)}$$

**Table 4. Static electrical characteristics (per diode)**

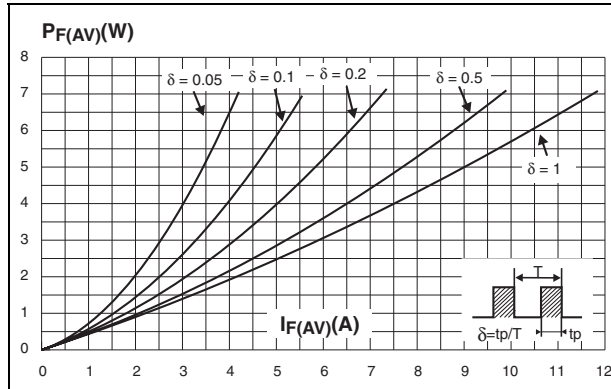
Symbol	Test conditions			Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ }^{\circ}\text{C}$	$V_R = V_{RRM}$	-	-	100	$\mu\text{A}$
		$T_j = 125\text{ }^{\circ}\text{C}$		-	7	15	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 125\text{ }^{\circ}\text{C}$	$I_F = 10\text{ A}$	-	0.5	0.57	V
		$T_j = 25\text{ }^{\circ}\text{C}$	$I_F = 20\text{ A}$	-	-	0.84	
		$T_j = 125\text{ }^{\circ}\text{C}$		-	0.65	0.72	

1. Pulse test :  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

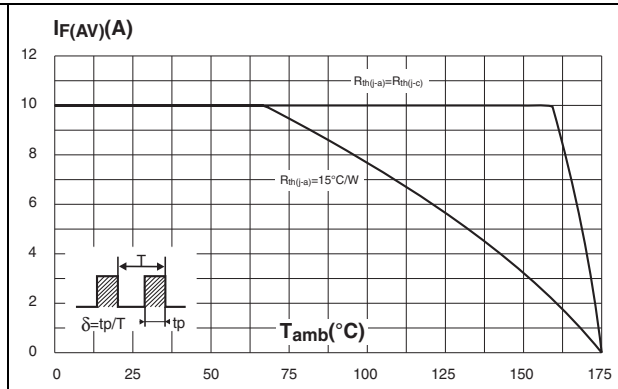
To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.015 I_{F(RMS)}^2$$

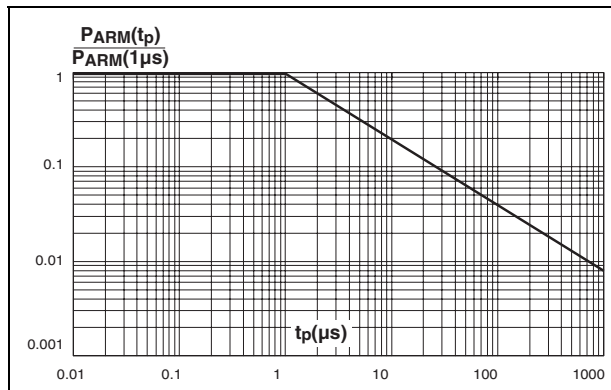
**Figure 1. Average forward power dissipation versus average forward current (per diode)**



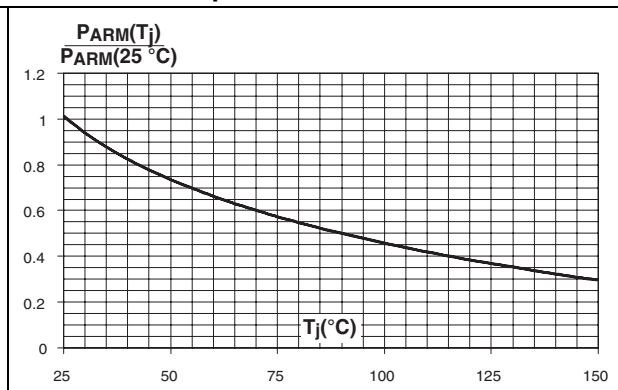
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode)**



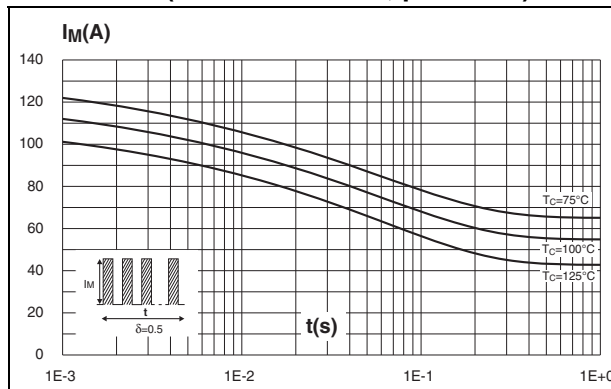
**Figure 3. Normalized avalanche power derating versus pulse duration**



**Figure 4. Normalized avalanche power derating versus junction temperature**



**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)**



**Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration**

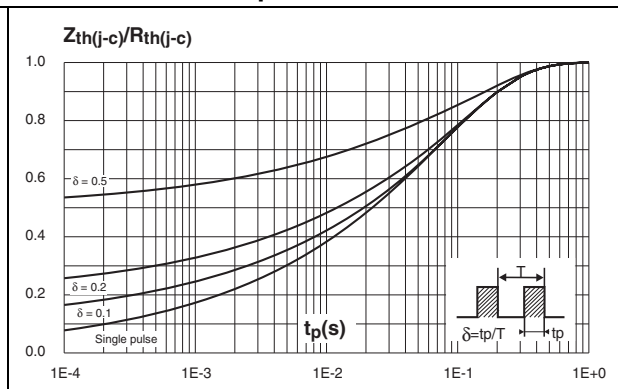


Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)

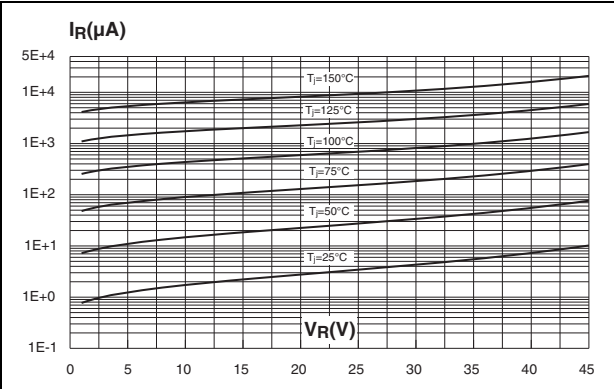


Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)

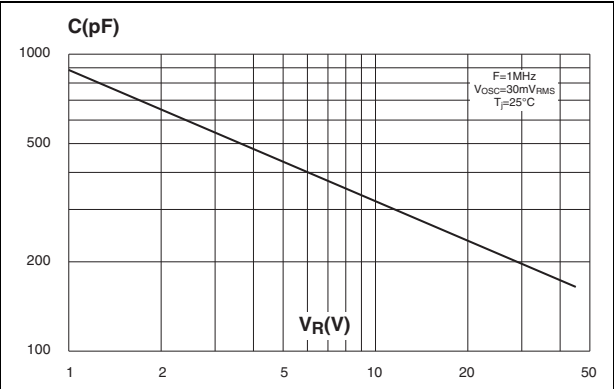


Figure 9. Forward voltage drop versus forward current (maximum values, per diode)

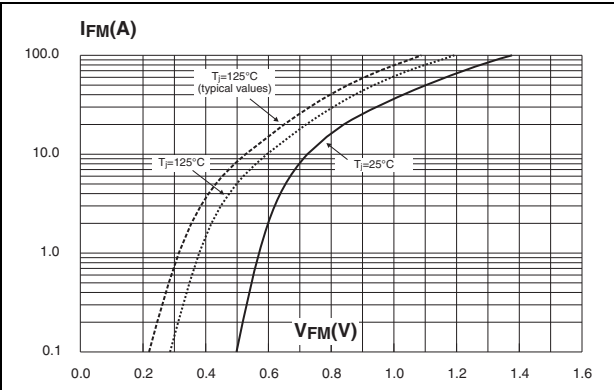
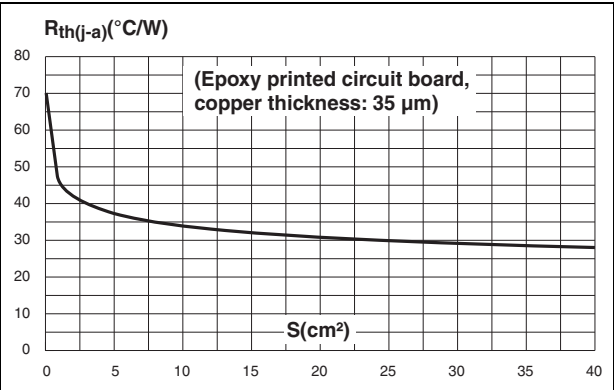


Figure 10. Thermal resistance junction to ambient versus copper surface under tab



## 2 Package information

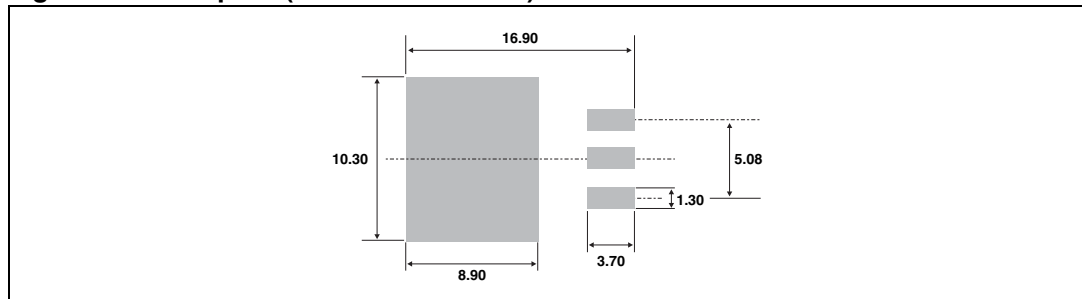
- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

**Table 5. D<sup>2</sup>PAK dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

**Figure 11. Footprint (dimensions in mm)**



### 3 Ordering information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS2045CGY-TR	STPS2045CGY	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel

### 4 Revision history

**Table 7. Document revision history**

Date	Revision	Changes
24-May-2011	1	Initial release.

**Please Read Carefully:**

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

**UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.**

**UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.**

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2011 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)